

## Advanced Power MOSFET

## IRFM220A

### FEATURES

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 10  $\mu\text{A}$  (Max.) @  $V_{DS} = 200\text{V}$
- Low  $R_{DS(\text{ON})}$  : 0.626  $\Omega$  (Typ.)

$BV_{DSS} = 200\text{ V}$   
 $R_{DS(\text{on})} = 0.8\ \Omega$   
 $I_D = 1.13\text{ A}$

SOT-223



1. Gate 2. Drain 3. Source

### Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
$V_{DSS}$	Drain-to-Source Voltage	200	V
$I_D$	Continuous Drain Current ( $T_A=25^\circ\text{C}$ )	1.13	A
	Continuous Drain Current ( $T_A=70^\circ\text{C}$ )	0.9	
$I_{DM}$	Drain Current-Pulsed	9	A
$V_{GS}$	Gate-to-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy	77	mJ
$I_{AR}$	Avalanche Current	1.13	A
$E_{AR}$	Repetitive Avalanche Energy	0.24	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$	5.0	V/ns
$P_D$	Total Power Dissipation ( $T_A=25^\circ\text{C}$ ) *	2.4	W
	Linear Derating Factor *	0.019	$\text{W}/^\circ\text{C}$
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temp. for Soldering Purposes, 1/8 " from case for 5-seconds	300	

### Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient *	--	52	$^\circ\text{C}/\text{W}$

\* When mounted on the minimum pad size recommended (PCB Mount).

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## Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	200	--	--	V	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$
$\Delta \text{BV} / \Delta T_J$	Breakdown Voltage Temp. Coeff.	--	0.24	--	$\text{V}^\circ\text{C}$	$\text{I}_D=250 \mu\text{A}$ See Fig 7
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	2.0	--	4.0	V	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=250 \mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage , Forward	--	--	100	nA	$\text{V}_{\text{GS}}=30\text{V}$
	Gate-Source Leakage , Reverse	--	--	-100		$\text{V}_{\text{GS}}=-30\text{V}$
$\text{I}_{\text{DSS}}$	Drain-to-Source Leakage Current	--	--	10	$\mu\text{A}$	$\text{V}_{\text{DS}}=200\text{V}$
		--	--	100		$\text{V}_{\text{DS}}=160\text{V}, T_A=125^\circ\text{C}$
$\text{R}_{\text{DS(on)}}$	Static Drain-Source On-State Resistance	--	--	0.8	$\Omega$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=0.57\text{A}$ ④
$\text{g}_{\text{fs}}$	Forward Transconductance	--	1.36	--	$\text{S}$	$\text{V}_{\text{DS}}=40\text{V}, \text{I}_D=0.57\text{A}$ ④
$\text{C}_{\text{iss}}$	Input Capacitance	--	275	360	pF	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=25\text{V}, f = 1\text{MHz}$ See Fig 5
$\text{C}_{\text{oss}}$	Output Capacitance	--	55	65		
$\text{C}_{\text{rss}}$	Reverse Transfer Capacitance	--	25	30		
$t_{\text{d(on)}}$	Turn-On Delay Time	--	10	30	ns	$\text{V}_{\text{DD}}=100\text{V}, \text{I}_D=5\text{A},$ $\text{R}_G=18\Omega$ See Fig 13 ④ ⑤
$t_r$	Rise Time	--	11	30		
$t_{\text{d(off)}}$	Turn-Off Delay Time	--	26	60		
$t_f$	Fall Time	--	15	40		
$\text{Q}_g$	Total Gate Charge	--	12	17	nC	$\text{V}_{\text{DS}}=160\text{V}, \text{V}_{\text{GS}}=10\text{V},$ $\text{I}_D=5\text{A}$ See Fig 6 & Fig 12 ④ ⑤
$\text{Q}_{\text{gs}}$	Gate-Source Charge	--	2.4	--		
$\text{Q}_{\text{gd}}$	Gate-Drain("Miller") Charge	--	6.2	--		

## Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
$\text{I}_s$	Continuous Source Current	--	--	1.13	A	Integral reverse pn-diode in the MOSFET
$\text{I}_{\text{SM}}$	Pulsed-Source Current ①	--	--	9		
$\text{V}_{\text{SD}}$	Diode Forward Voltage ④	--	--	1.5	V	$T_J=25^\circ\text{C}, \text{I}_s=1.13\text{A}, \text{V}_{\text{GS}}=0\text{V}$
$t_{\text{rr}}$	Reverse Recovery Time	--	122	--	ns	$T_J=25^\circ\text{C}, \text{I}_F=5\text{A}$
$\text{Q}_{\text{rr}}$	Reverse Recovery Charge	--	0.51	--	$\mu\text{C}$	$d\text{I}_F/dt=100\text{A}/\mu\text{s}$ ④

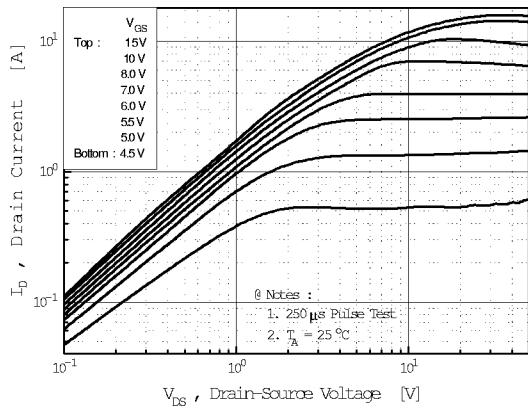
### Notes :

- ① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- ②  $L=90\text{mH}, \text{I}_{\text{AS}}=1.13\text{A}, \text{V}_{\text{DD}}=50\text{V}, \text{R}_G=2\Omega, \text{Starting } T_J=25^\circ\text{C}$
- ③  $\text{I}_{\text{SD}} \leq 5\text{A}, d\text{I}/dt \leq 180\text{A}/\mu\text{s}, \text{V}_{\text{DD}} \leq \text{BV}_{\text{DSS}}$ , Starting  $T_J=25^\circ\text{C}$
- ④ Pulse Test : Pulse Width =  $250\mu\text{s}$ , Duty Cycle  $\leq 2\%$
- ⑤ Essentially Independent of Operating Temperature

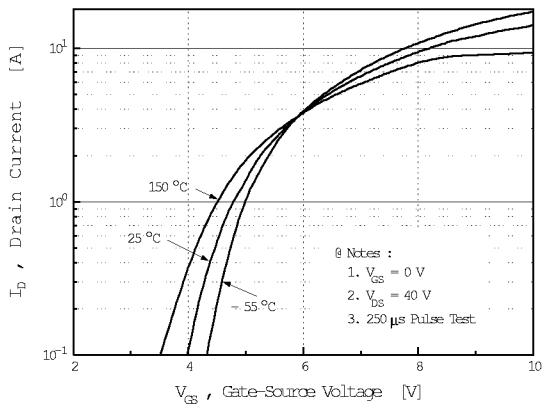
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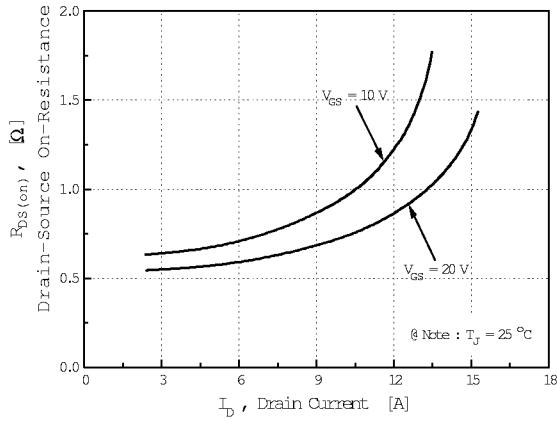
**Fig 1. Output Characteristics**



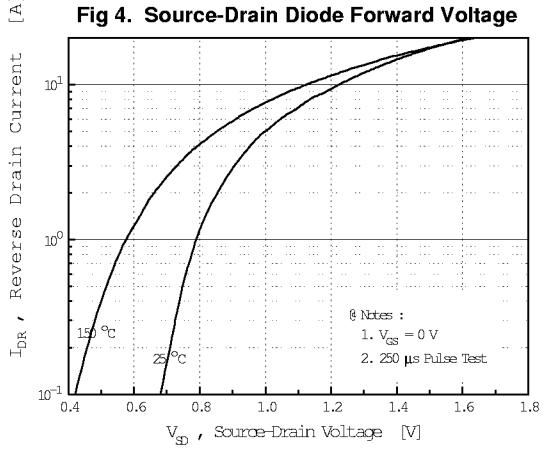
**Fig 2. Transfer Characteristics**



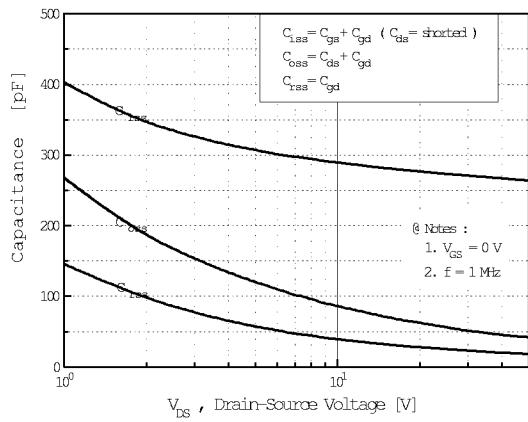
**Fig 3. On-Resistance vs. Drain Current**



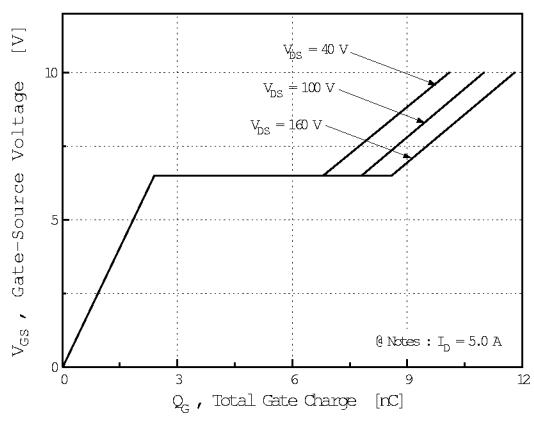
**Fig 4. Source-Drain Diode Forward Voltage**



**Fig 5. Capacitance vs. Drain-Source Voltage**

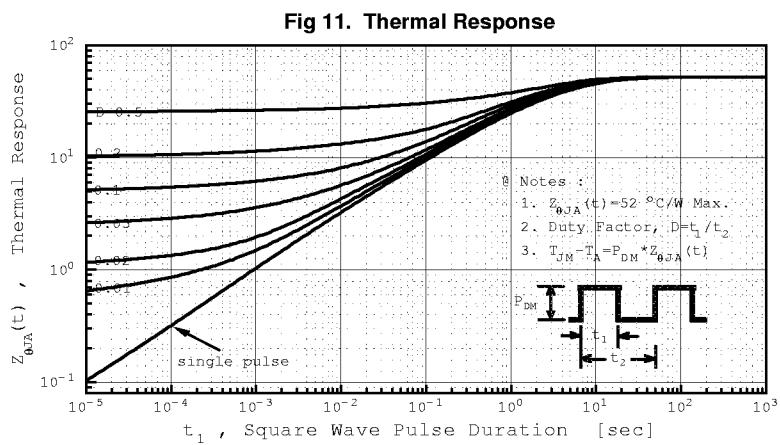
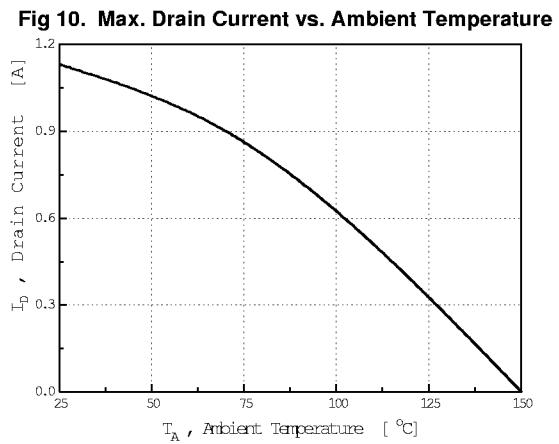
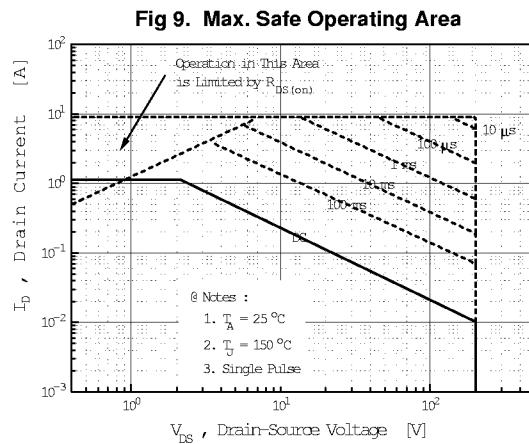
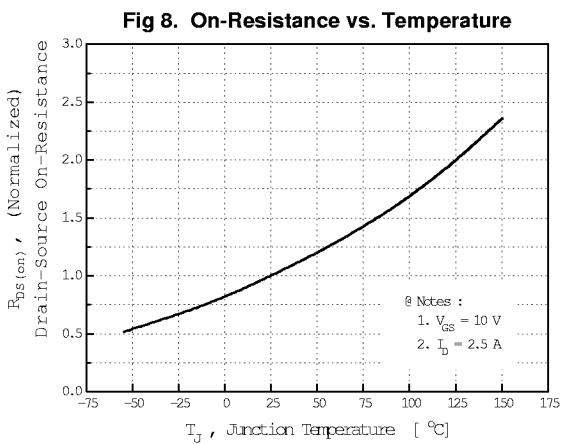
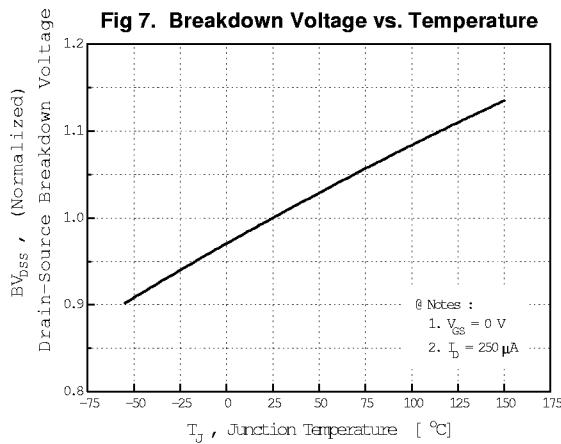


**Fig 6. Gate Charge vs. Gate-Source Voltage**



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Fig 12. Gate Charge Test Circuit & Waveform

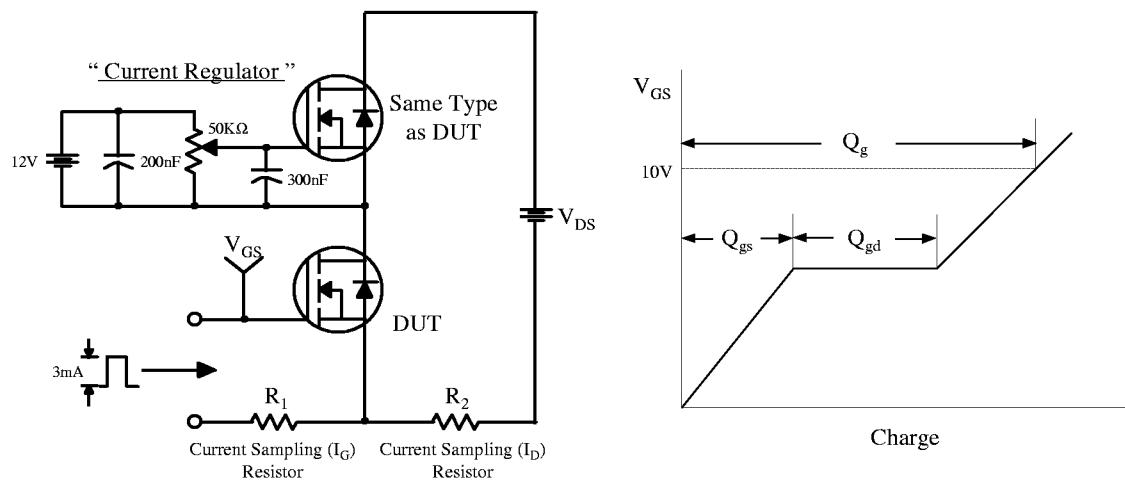


Fig 13. Resistive Switching Test Circuit & Waveforms

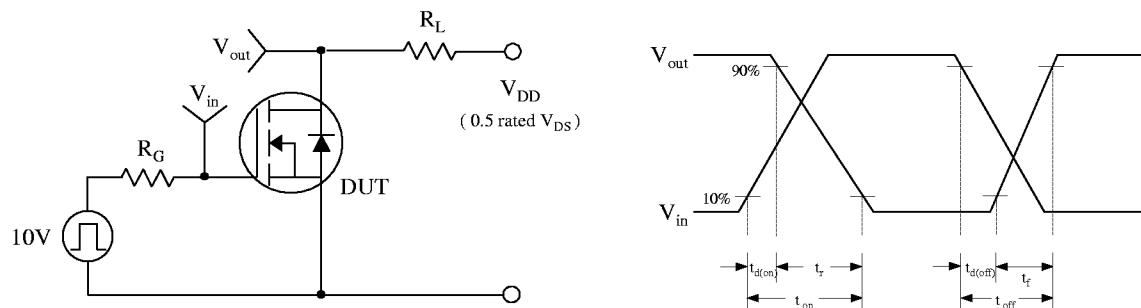
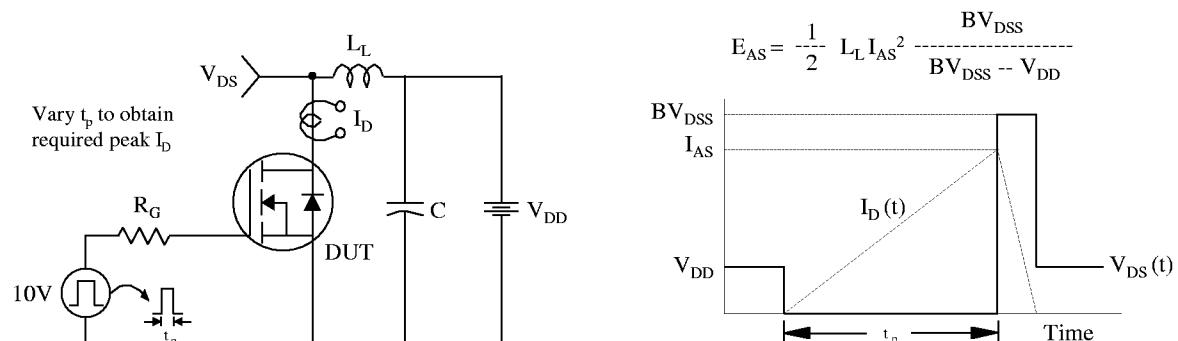


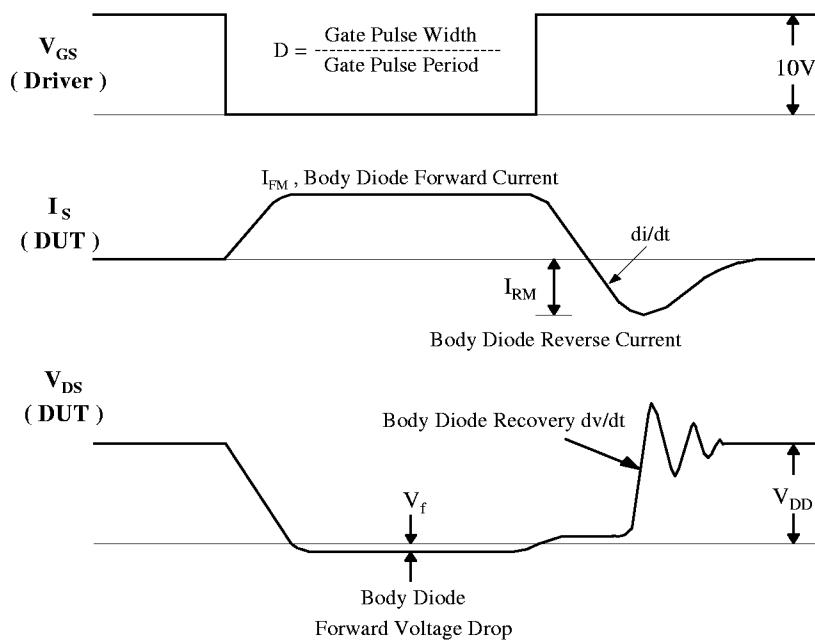
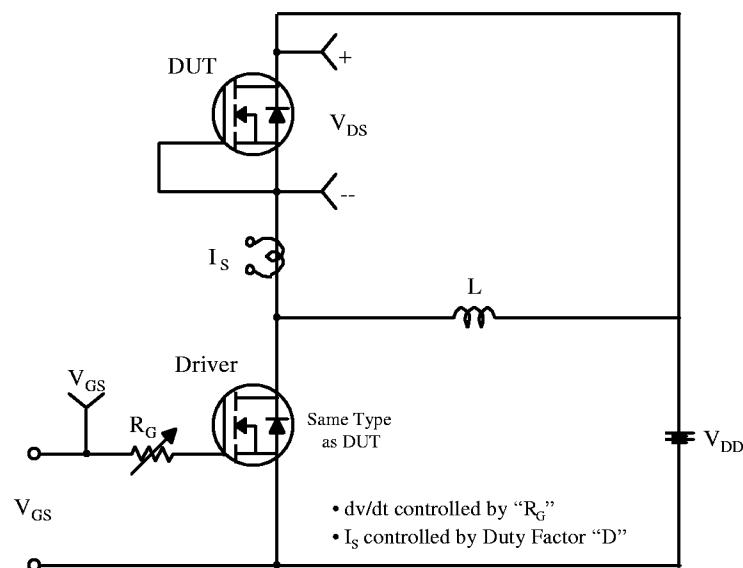
Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



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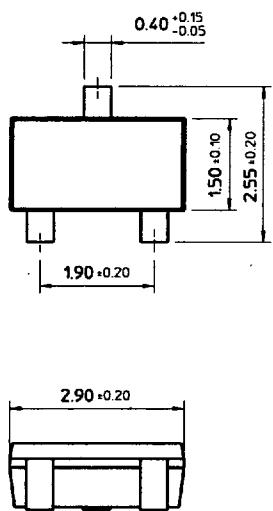
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Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

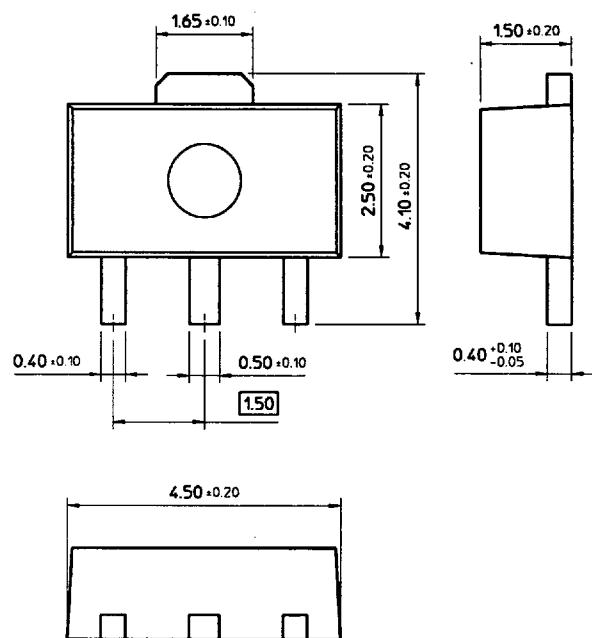


Dimensions in Millimeters

SOT-23



SOT-89



SOT-223

